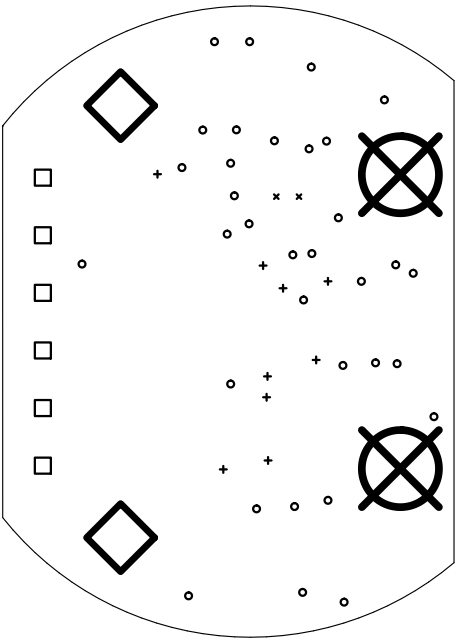


BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	62.99 mils
Board overall dimensions:	783.63 mils x 1096.00 mils		
Min track/spacing:	10.00 mils / 9.50 mils	Min hole diameter:	10.00 mils
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Blue	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric 1	prepreg	FR4	3.93701 mils	Not specified	4.5	0.02
In1.Cu	copper		1.37795 mils		1	0
Dielectric 2	core	FR4	48.8189 mils	Not specified	4.5	0.02
In2.Cu	copper		1.37795 mils		1	0
Dielectric 3	prepreg	FR4	3.93701 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Blue	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0



Drill Map:

- × 0.200mm / 0.0079" (2 holes)
- 0.300mm / 0.0118" (33 holes)
- + 0.305mm / 0.0120" (9 holes)
- 1.000mm / 0.0394" (6 holes)
- ◇ 3.000mm / 0.1181" (2 holes)
- ⊗ 3.400mm / 0.1339" (2 holes) (not plated)

NOTES:

1. LAYERS: 4
2. PCB THICKNESS: 1.6mm
3. PCB COLOR: BLUE
4. SILKSCREEN: WHITE
5. MATERIAL TYPE: FR4 TG-155
6. SURFACE FINISH: ENIG
7. OUTER COPPER WEIGHT: 1oz
8. INNER COPPER WEIGHT: 0.5oz
9. IMPEDANCE CONTROL: NO
10. VIA COVERING: PLUGGED
11. MIN VIA HOLE DIA: 0.2mm
12. BOARD OUTLINE TOLERANCE: +/-0.2mm